

Title (en)
TEMPERATURE CONTROL METHOD, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, TEMPERATURE CONTROL SYSTEM,
SUBSTRATE PROCESSING APPARATUS, AND PROGRAM

Title (de)
TEMPERATURSTEUERUNGSVERFAHREN, VERFAHREN ZUR HERSTELLUNG EINER HALBLEITERVORRICHTUNG,
TEMPERATURSTEUERUNGSSYSTEM, SUBSTRATVERARBEITUNGSVORRICHTUNG UND PROGRAMM

Title (fr)
PROCÉDÉ DE RÉGULATION DE TEMPÉRATURE, PROCÉDÉ DE FABRICATION DE DISPOSITIF À SEMI-CONDUCTEUR, SYSTÈME DE
RÉGULATION DE TEMPÉRATURE, APPAREIL DE TRAITEMENT DE SUBSTRAT ET PROGRAMME

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Application
EP 23220431 A 20231228

Priority
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Abstract (en)
According to one embodiment of the present disclosure, there is provided a technique of controlling a temperature of a substrate by using a moving average value calculated by performing a moving average process on temperature values detected by a temperature sensor installed to be rotatable together with a holder configured to hold the substrate.

IPC 8 full level
H01L 21/67 (2006.01)

CPC (source: EP KR US)
C23C 16/46 (2013.01 - KR); **C23C 16/52** (2013.01 - KR); **G01K 1/14** (2013.01 - KR); **H01L 21/67109** (2013.01 - KR);
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H01L 21/67757 (2013.01 - KR)

Citation (search report)

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- [A] US 2018350569 A1 20181206 - KANEKO KENGO [JP], et al
- [A] US 2020126834 A1 20200423 - YAMAGUCHI SHUNJI [JP], et al
- [A] US 2008208385 A1 20080828 - SAKAMOTO KOICHI [JP], et al
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Designated extension state (EPC)
BA

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KH MA MD TN

DOCDB simple family (publication)
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US 2024242986 A1 20240718

DOCDB simple family (application)
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US 202318398292 A 20231228